

# 2010 International Electrostatic Discharge Workshop



## Call For Presentations

4th Annual International Electrostatic Discharge Workshop

May 10-13, 2010 in Tutzing, Germany

<http://www.esda.org/iew.htm>

<http://www.ev-akademie-tutzing.de/>

## 2010 International Electrostatic Discharge Workshop

The 2010 International ESD Workshop will build upon the highly successful workshops held from 2007 to 2009. The 2010 workshop will continue to focus on robust design and test of ESD protection for state-of-the-art integrated circuits as well as advanced semiconductor system on chip (SOC) and system in package (SIP) applications. For the fourth annual workshop we are inviting a focus on the increasing importance of system level ESD design and test as well as the relationship between system level

ESD and component level ESD. Invited presentations addressing system level ESD aspects in automotive, avionic and health industry are planned. Through the technical presentations solicited here, as well as invited seminars, poster sessions, discussion groups and special interest groups, a unique and informal environment is provided for understanding and sharing ESD technology. All workshop activities take place in a relaxed setting that promotes an atmosphere of interactive learning

and helpful discussions. To enhance the interactive nature of the workshop in 2010 a stronger emphasis will be placed on poster presentations. All refereed poster presentations will have a brief podium presentation to explain the nature of their poster and invite the attendees to visit the poster for a period of stimulating interaction. The International ESD Workshop (IEW) is closely aligned with the EOS/ESD Symposium for collaborative conference activities.

### Abstract Submission Deadline Nov. 20, 2009

We invite you to submit a presentation proposal addressing any of the following topics:

#### Novel Design Concepts

New protection device and circuit concepts, high sensitivity & high speed circuit challenges, off-the-wall ideas

#### Special Custom Design Approaches

High voltage application designs, protection design for analog circuits, Bi-CMOS and Bipolar protection, GaAs protection

#### Technology Integration Issues

ESD sensitivity with technology transfers, qualification challenges for different fabs, unusual problems of process interaction with ESD, process monitor methods

#### Failure Analysis

New techniques to detect ESD failures, correlation between HBM/CDM/TLP with physical FA, unusual failure modes

#### Test Structures

Design of standard structures for It2, gate oxide and metal current density monitor; special VF-TLP test structure design and analysis

#### Simulation Tools

TCAD interpretation examples, device behavior under ESD like conditions, standard SPICE simulation techniques to verify ESD designs, ESD checking tool development

#### ESD Testing Characterization and Tester Issues

Failure debug procedures, correlation of TLP and HBM and correlation of VF-TLP and CDM. Tester to tester correlation, ESD tester artifacts, and test standards issues

#### System Level ESD Issues

On-chip and on-board IEC protection device techniques, cable discharge, transient latch-up effects, system failure cases

#### Unresolved ESD Issues

Random and unrepeatable ESD failures, issues with ESD standards, ESD data statistics

### Submission Instructions

Your abstract (two pages including figures) must clearly present the data and the significance of the results. Submitted abstracts will be considered for both podium and poster presentation. Please email your presentation abstract including title, author affiliation and email address to [iew@esda.org](mailto:iew@esda.org) by the November 20, 2009 deadline. The required format is pdf® (Adobe Acrobat®). Notification of acceptance will occur by December 11, 2009. Final presentations for the workshop in PowerPoint® format must be received by April 9, 2010. These PowerPoint® slides will be included in the Presentation Handout along with a CD-ROM that will be distributed during the Workshop. Refereed poster presentations will be included in the CD-ROM. There will be no formal report published. Due to an agreed alignment through the ESD Association, presentation of your work at the IEW will not preclude a subsequent, but more detailed, submission to the EOS/ESD Symposium. For any questions please contact the Technical Program Chair, Gaudenzio Meneghesso ([gaudenzio.meneghesso@dei.unipd.it](mailto:gaudenzio.meneghesso@dei.unipd.it))



## More Information

The IEW encourages student submissions by providing a 50% discount in registration fees for a limited number of student presenters. Proof of student status must be submitted along with the abstracts for oral presentations.

Please check our web page at <http://www.esda.org/iew.htm> for regularly updated information on the Workshop. As it becomes available, we will post information on the full technical program including the seminar topics, the keynote speaker, the poster sessions, as well as the discussion group and special interest group topics. In addition to the peer-reviewed presentations, attendees will also have the option to present non-peer-reviewed posters at the Workshop. If you have any questions about the Posters sessions please contact the Posters Chair, [natarajanmi@charteredsemi.com](mailto:natarajanmi@charteredsemi.com). Please also look to the web page for information on Workshop registration, the location of Tutzing and the Munich area.

## Lodging & Facilities

Located on the shores of Lake Starnberg, 30 kilometers Southwest of Munich, lies the Tutzing estate and its 18th century mansion. It has been chosen as the venue of our workshop with its modern conference rooms and facilities. The on-site single and double bedrooms provide a comfortable stay within the quietness of the private park around the castle. From the balconies and the patios there is a magnificent view of Bavarian Alps. The spirit of this place encourages thoughtful discussions and intensive interaction. Lodging and all meals will be included in the registration costs for the Workshop. Spouses are welcome.

<http://www.ev-akademie-tutzing.de/>

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